查询TN0200K-T1-E3供应商

**VISHAY** 

#### **TN0200K**

RoHS COMPLIANT

Vishay Siliconix

### WW.DZSC.C N-Channel 20-V (D-S) MOSFETs

PRODUCT	SUMMARY		FEATURES UNW DZSD.		
V <sub>DS</sub> (V)	r <sub>DS(on)</sub> (Ω)	I <sub>D</sub> (A)	TrenchFET <sup>®</sup> Power MOSFET		
	0.4 at V <sub>GS</sub> = 4.5 V	0.73	ESD Protected: 4000 V		
20	0.5 at V <sub>GS</sub> = 2.5 V	0.65	APPLICATIONS		
			<ul> <li>Direct Logic-Level Interface: TTL/CMOS</li> <li>Drivers: Relays, Solenoids, Lamps, Hammers</li> <li>Battery Operated Systems, DC/DC Converters</li> <li>Solid-State Relays</li> <li>Load/Power Switching-Cell Phones, Pagers</li> </ul>		
G 1 S 2		Marking Code: K2ywl K2 = Part Number Code for v = Year Code v = Week Code = Lot Traceability			
	Top View		W.U.		

<b>ABSOLUTE MAXIMUM RATINGS</b> $T_A = 25 \degree C$ , u	nless otherwise	e noted			
Parameter	Symbol	Limit	Unit		
Drain-Source Voltage	V <sub>DS</sub>	20	v		
Gate-Source Voltage		V <sub>GS</sub>			± 8
Continuous Durin Coursent (T. 150 °C)b	T <sub>A</sub> = 25 °C	1000	0.73	1.00	
Continuous Drain Current (T <sub>J</sub> = 150 °C) <sup>b</sup>	T <sub>A</sub> = 70 °C	D	0.58		
Pulsed Drain Current <sup>a</sup>	192 14	I <sub>DM</sub>	4	A	
Continuous Source Current (Diode Conduction)		۱ <sub>S</sub>	0.3	A W	
Provide the second of the second	T <sub>A</sub> = 25 °C	PD	0.35	10/	
Power Dissipation <sup>b</sup>	T <sub>A</sub> = 70 °C	гD	0.22	vv	
Operating Junction and Storage Temperature Range	•	T <sub>J,</sub> T <sub>stg</sub>	- 55 to 150	°C	

THERMAL RESI	STANCE RATINGS			
Parameter		Symbol	Limit	Unit
Maximum Junction-to-A	mbient <sup>b</sup>	R <sub>thJA</sub>	357	°C/W

#### Notes PDF

a. Pulse width limited by maximum junction temperature.

b. Surface Mounted on FR4 Board,  $t \le 10$  sec. t.dzsc.com

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			Limits			
Parameter	Symbol	Test Conditions	Min	Тур	Мах	Unit
Static	· · ·					
Drain-Source Breakdown Voltage	V <sub>(BR)DSS</sub>	$V_{GS} = 0 V, I_{D} = 10 \mu A$	20			v
Gate-Threshold Voltage	V <sub>GS(th)</sub>	$V_{DS} = V_{GS}$ , $I_D = 50 \ \mu A$	0.45	0.6	1.0	
Gate-Body Leakage	I <sub>GSS</sub>	$V_{DS} = 0 V, V_{GS} = \pm 4.5 V$			± 5	
Zaus Oata Valtaga Dusia Ouwant		$V_{DS} = 20 V, V_{GS} = 0 V$			0.1	μA
Zero Gate Voltage Drain Current	IDSS	T <sub>J</sub> = 55 °C			10	
	I <sub>D(on)</sub>	$V_{DS} \ge 5$ V, $V_{GS} = 4.5$ V	2.5			A
On-State Drain Current <sup>a</sup>		$V_{DS} \ge 5$ V, $V_{GS} = 2.5$ V	1.5			
		$V_{GS} = 4.5 \text{ V}, I_D = 0.6 \text{ A}$	4.5 V, I <sub>D</sub> = 0.6 A	0.2	0.4	Ω
Drain-Source On-Resistance <sup>a</sup>	r <sub>DS(on)</sub>	$V_{GS} = 2.5 \text{ V}, I_D = 0.6 \text{ A}$		0.25	0.5	
Forward Transconductance <sup>a</sup>	9 <sub>fs</sub>	$V_{DS} = 5 \text{ V}, \text{ I}_{D} = 0.6 \text{ A}$		2.2		S
Diode Forward Voltage <sup>a</sup>	V <sub>SD</sub>	$I_{\rm S} = 0.3$ A, $V_{\rm GS} = 0$ V		0.8	1.2	V
Dynamic <sup>b</sup>	· · ·					
Total Gate Charge	Qg			1400	2000	
Gate-Source Charge	Q <sub>gs</sub>	$V_{DS} = 10 \text{ V}, \text{ V}_{GS} = 4.5 \text{ V}$ $I_{D} = 0.6 \text{ A}$		190		рС
Gate-Drain Charge	Q <sub>gd</sub>	10 - 0.0 / 1		300		1
Gate Resistance	R <sub>g</sub>			105		Ω
Turn-On Delay Time	t <sub>d(on)</sub>			17	25	
Rise Time t <sub>r</sub>		$V_{DD} = 10 \text{ V}, \text{ R}_{L} = 16 \Omega$ $I_{D} \cong 0.6 \text{ A}, V_{GEN} = 4.5 \text{ V}$		20	30	1
Turn-Off Delay Time	t <sub>d(off)</sub>	$I_D \cong 0.6 \text{ A}, V_{\text{GEN}} = 4.5 \text{ V}$ $R_a = 6 \Omega$		55	85	- ns
Fall TIme	t <sub>f</sub>	- ·g		30	45	

New Product

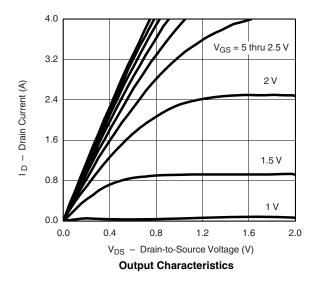
Notes:

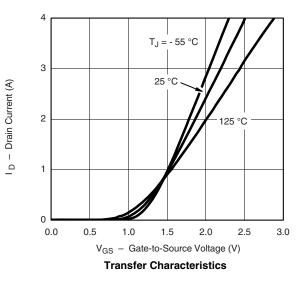
a. Pulse test: PW  $\leq$  300  $\mu s$  duty cycle  $\leq$  2 %.

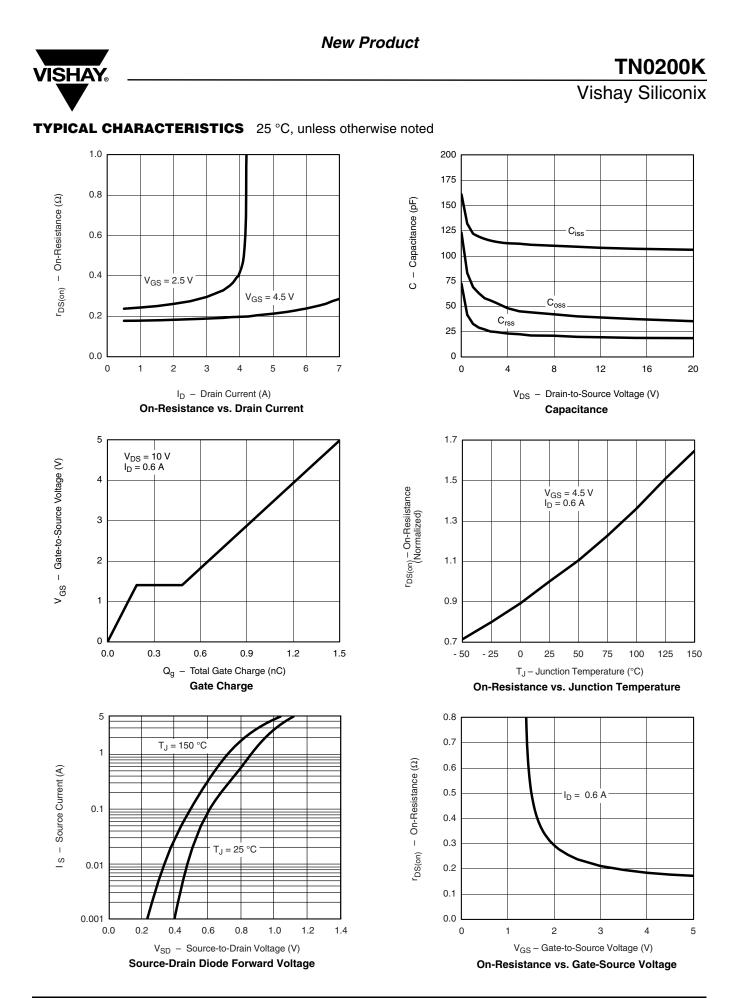
b. Guaranteed by design, not subject to production testing.

Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

#### TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted





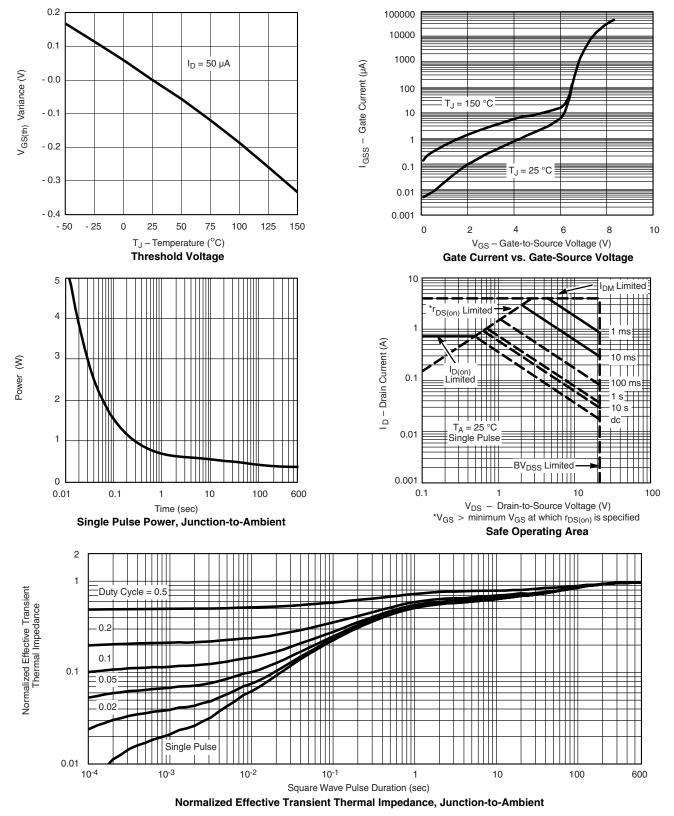


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Vishay Siliconix maintains worldwide manufacturing capability. Products may be manufactured at one of several qualified locations. Reliability data for Silicon Technology and Package Reliability represent a composite of all qualified locations. For related documents such as package/tape drawings, part marking, and reliability data, see http://www.vishay.com/ppg?72678.



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